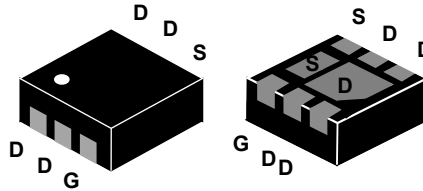
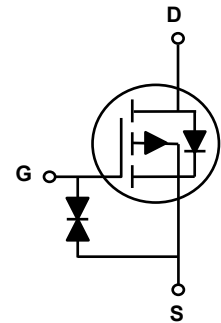


### Main Product Characteristics

$V_{(BR)DSS}$	-20V
$R_{DS(ON)}$	33mΩ.Max.)
$I_D$	-8.0A



DFN2x2-6L 2EP



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFB2033E utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous ( $T_A=25^{\circ}C$ )	$I_D$	-8.0	A
Drain Current-Continuous ( $T_A=100^{\circ}C$ )		-4.8	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-24	A
Power Dissipation ( $T_A=25^{\circ}C$ )	$P_D$	1.8	W
Power Dissipation-Derate above 25°C		0.015	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	80	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

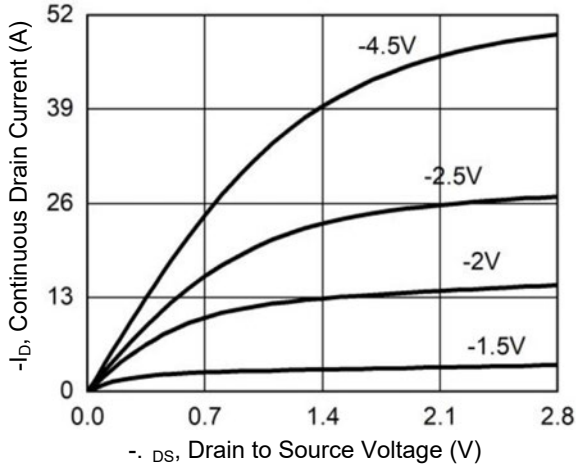
**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS}=0V, I_D=250\mu A$	-20	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1mA$	-	-0.02	-	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V,$ $T_J=25^\circ\text{C}$	-	-	-1	$\mu A$
		$V_{DS}=-16V, V_{GS}=0V,$ $T_J=125^\circ\text{C}$	-	-	-10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	$\pm 10$	$\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-2A$	-	26	33	$m\Omega$
		$V_{GS}=-2.5V, I_D=-1A$	-	36	41	$m\Omega$
		$V_{GS}=-1.8V, I_D=-1A$	-	52	69	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.55	-	-1	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-2	-	$mV/^\circ\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=-5V, I_D=-5A$	-	15	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{DS}=-10V, I_D=-5A,$ $V_{GS}=-4.5V$	-	9.1	-	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{gs}$		-	1.6	-	
Gate-Drain Charge <sup>2,3</sup>	$Q_{gd}$		-	1.6	-	
Turn-On Delay Time <sup>2,3</sup>	$t_{d(on)}$	$V_{DD}=-10V, R_G=3\Omega,$ $V_{GS}=-4.5V, I_D=-5A$	-	11	-	nS
Rise Time <sup>2,3</sup>	$t_r$		-	34	-	
Turn-Off Delay Time <sup>2,3</sup>	$t_{d(off)}$		-	21	-	
Fall Time <sup>2,3</sup>	$t_f$		-	11	-	
Input Capacitance	$C_{iss}$	$V_{DS}=-10V, V_{GS}=0V,$ $F=1MHz$	-	390	-	pF
Output Capacitance	$C_{oss}$		-	106	-	
Reverse Transfer Capacitance	$C_{rss}$		-	42	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V,$ Force Current	-	-	-8	A
Pulsed Source Current	$I_{SM}$		-	-	-24	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A,$ $T_J=25^\circ\text{C}$	-	-	-1.3	V
Reverse Recovery Time	$t_{rr}$	$I_F=-5AV,$ $di/dt=100A/us$	-	170	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	60	-	nc

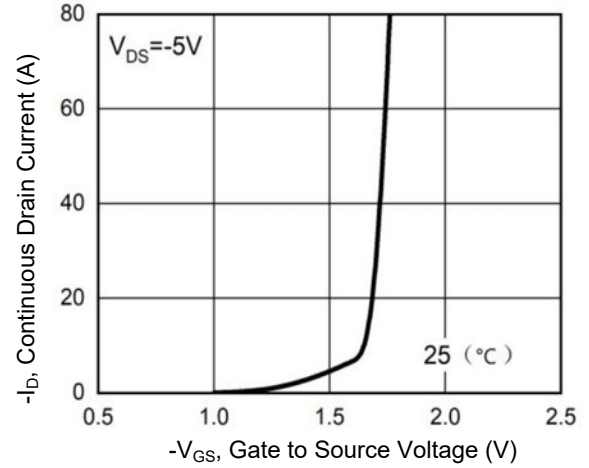
Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. Pulse test: pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operation temperature.

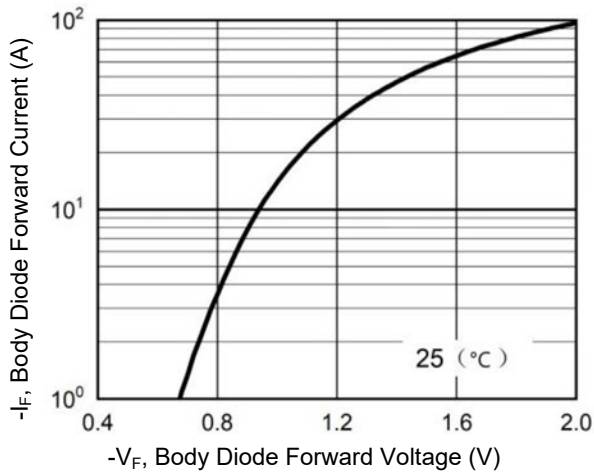
### Typical Electrical and Thermal Characteristic Curves



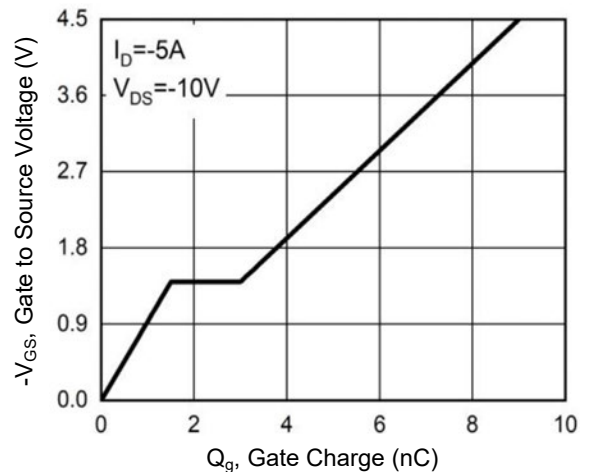
**Figure 1. Output Characteristics**



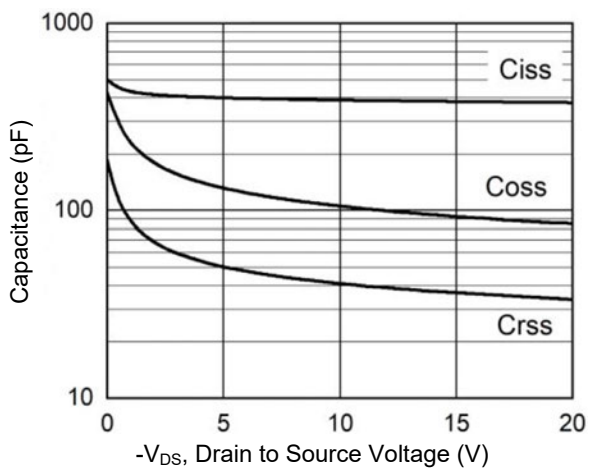
**Figure 2. Transfer Characteristics**



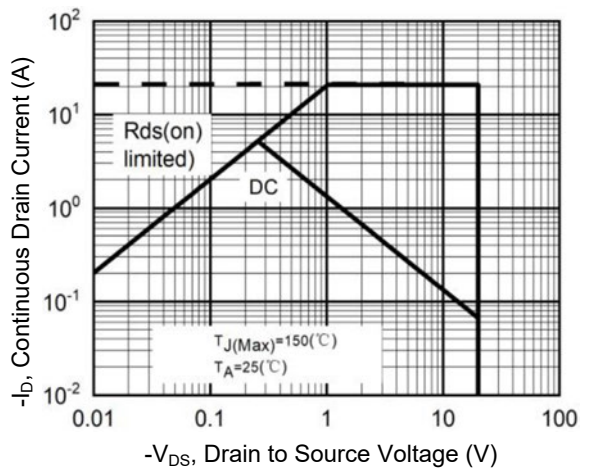
**Figure 3. Body Diode Characteristics**



**Figure 4. Gate Charge Waveform**

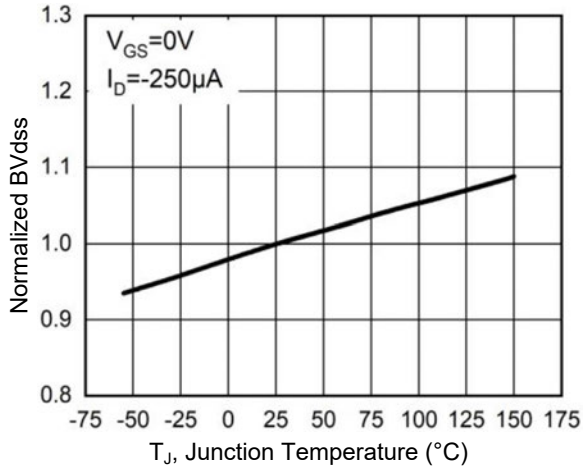


**Figure 5. Capacitance Characteristics**

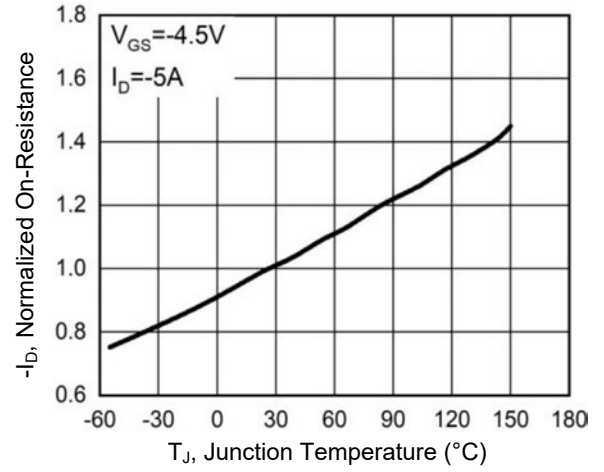


**Figure 6. Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**

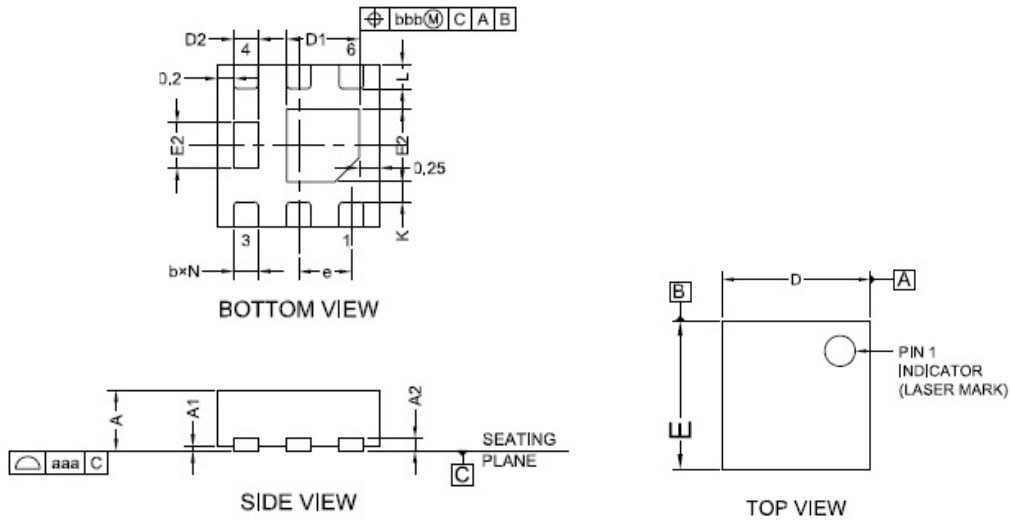


**Figure 7. Normalized BVdss vs. T<sub>J</sub>**



**Figure 8. Normalized Ron vs. T<sub>J</sub>**

## Package Outline Dimensions (DFN2x2-6L 2EP)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.500	0.600	0.020	0.024
A1	0.000	0.050	0.000	0.002
A2	0.152 REF		0.006 REF	
b	0.250	0.350	0.010	0.014
D	1.950	2.050	0.077	0.081
D1	0.800	1.000	0.031	0.039
D2	0.250	0.350	0.010	0.014
E	1.950	2.050	0.077	0.081
E1	0.800	1.000	0.031	0.039
E2	0.460	0.660	0.018	0.026
e	0.650 BSC		0.026 BSC	
L	0.250	0.350	0.010	0.014
J	0.400 BSC		0.016 BSC	
K	0.200 MIN		0.008 MIN	
N	6.000		6.00	
aaa	0.080		0.003	
bbb	0.100		0.004	

## Order Information

Device	Package	Marking	Quantity	Carrier
GSFB2033E	DFN2x2-6L 2EP	B2033E	3,000pcs / Reel	Tape & Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)